

# SN54136, SN54LS136, SN74136, SN74LS136 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES WITH OPEN-COLLECTOR OUTPUTS

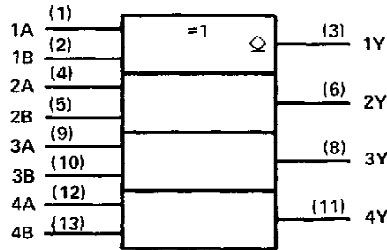
DECEMBER 1972 - REVISED MARCH 1988

FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

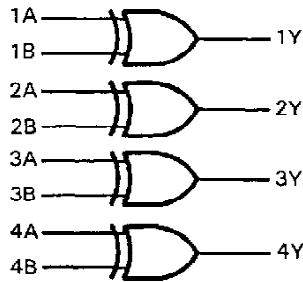
H = high level, L = low level

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

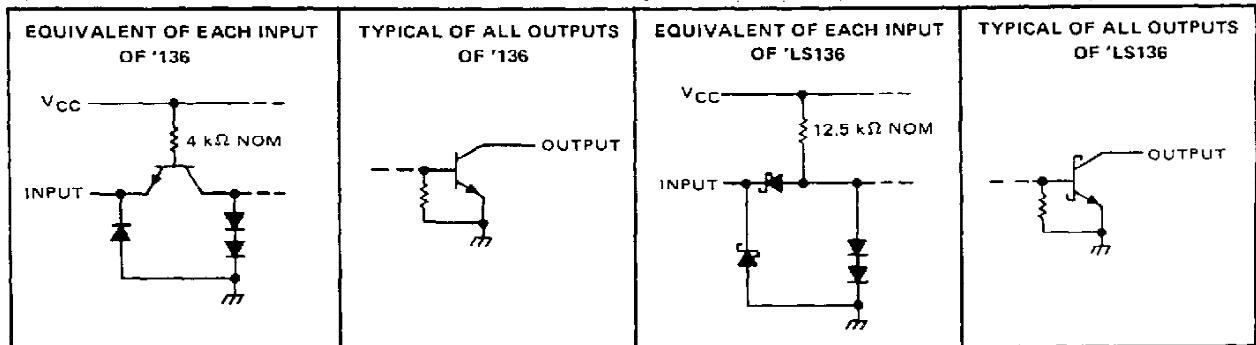
logic diagram (each gate)



positive logic

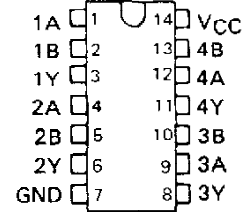
$$Y = A \oplus B = \bar{A} \cdot B + A \cdot \bar{B}$$

schematics of inputs and outputs

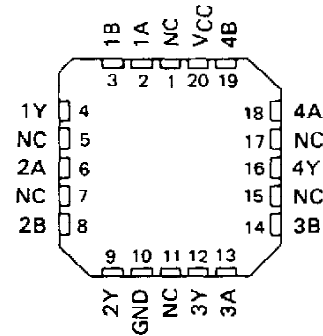


Resistor values shown are nominal.

SN54136, SN54LS136 . . . J OR W PACKAGE  
SN74136 . . . N PACKAGE  
SN74LS136 . . . D OR N PACKAGE  
(TOP VIEW)



SN54LS136 . . . FK PACKAGE  
(TOP VIEW)



NC - No internal connection

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# SN54136, SN74136 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES WITH OPEN-COLLECTOR OUTPUTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54136	-55°C to 125°C
SN74136	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

### recommended operating conditions

	SN54136			SN74136			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, $V_{CC}$	4.5	5	5.5	4.75	5	5.25	V
High-level input voltage, $V_{IH}$	2			2			V
Low-level input voltage, $V_{IL}$			0.8			0.8	V
High-level output voltage, $V_{OH}$			5.5			5.5	V
Low-level output current, $I_{OL}$			16			16	mA
Operating free-air temperature, $T_A$	-55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>†</sup>	SN54136			SN74136			UNIT	
		MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX		
$V_{IK}$	$V_{CC} = \text{MIN}$ , $I_I = -8 \text{ mA}$			-1.5			-1.5	V	
$I_{OH}$	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $V_{OH} = 5.5 \text{ V}$						0.25	mA	
	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = 0.7 \text{ V}$ , $V_{OH} = 5.5 \text{ V}$			0.25					
$V_{OL}$	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OL} = 16 \text{ mA}$			0.2	0.4		0.2	0.4	V
$I_I$	$V_{CC} = \text{MAX}$ , $V_I = 5.5 \text{ V}$			1			1	mA	
$I_{IH}$	$V_{CC} = \text{MAX}$ , $V_I = 2.4 \text{ V}$			40			40	$\mu\text{A}$	
$I_{IL}$	$V_{CC} = \text{MAX}$ , $V_I = 0.4 \text{ V}$			-1.6			-1.6	mA	
$I_{CC}$	$V_{CC} = \text{MAX}$ , See Note 2			30	43		30	50	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

NOTE 2:  $I_{CC}$  is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^\circ\text{C}$

PARAMETER <sup>¶</sup>	FROM (INPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT	
		Other input low	Other input high					
$t_{PLH}$	A or B	Other input low	$C_L = 15 \text{ pF}$ , $R_L = 400 \Omega$ , See Note 3			12	18	ns
$t_{PHL}$						39	50	
$t_{PLH}$	A or B	Other input high	See Note 3			14	22	ns
$t_{PHL}$						42	55	

<sup>¶</sup>  $t_{PLH}$  propagation delay time, low-to-high-level output

$t_{PHL}$  propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS136, SN74LS136

## QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES WITH OPEN-COLLECTOR OUTPUTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS136	-55°C to 125°C
SN74LS136	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

### recommended operating conditions

	SN54LS136			SN74LS136			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, $V_{CC}$	4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, $V_{OH}$			5.5			5.5	V
Low-level output current, $I_{OL}$			4			8	mA
Operating free-air temperature, $T_A$	-55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS136		SN74LS136		UNIT	
		MIN	TYP‡	MAX	MIN		TYP‡
$V_{IH}$ High-level input voltage		2			2	V	
$V_{IL}$ Low-level input voltage				0.7		0.8	V
$V_{IK}$ Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.5		-1.5	V
$I_{OH}$ High-level output current	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, V_{OH} = 5.5 \text{ V}$			100		100	μA
$V_{OL}$ Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}$	$I_{OL} = 4 \text{ mA}$		0.25	0.4	V	
		$I_{OL} = 8 \text{ mA}$			0.35 0.5		
$I_I$ Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$			0.2		0.2	mA
$I_{IH}$ High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			40		40	μA
$I_{IL}$ Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			-0.8		-0.8	mA
$I_{CC}$ Supply current	$V_{CC} = \text{MAX}, \text{ See Note 2}$	6.1	10		6.1	10	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

‡ All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ .

NOTE 2:  $I_{CC}$  is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

### switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

PARAMETER‡	FROM (INPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{PLH}$	A or B	Other input low	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega,$ (See Note 3)		18	30	ns
$t_{PHL}$					18	30	
$t_{PLH}$	A or B	Other input high	(See Note 3)		18	30	ns
$t_{PHL}$					18	30	

†  $t_{PLH}$  propagation delay time, low-to-high-level output

‡  $t_{PHL}$  propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9231901MCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9231901MC A SNJ54LS136J	<a href="#">Samples</a>
SN54LS136J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS136J	<a href="#">Samples</a>
SN74LS136D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS136	<a href="#">Samples</a>
SN74LS136DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS136	<a href="#">Samples</a>
SN74LS136DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS136	<a href="#">Samples</a>
SN74LS136N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS136N	<a href="#">Samples</a>
SN74LS136NE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS136N	<a href="#">Samples</a>
SN74LS136NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS136	<a href="#">Samples</a>
SNJ54LS136J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9231901MC A SNJ54LS136J	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54LS136, SN74LS136 :**

- Catalog: [SN74LS136](#)
- Military: [SN54LS136](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS136DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS136NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS136DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS136NSR	SO	NS	14	2000	367.0	367.0	38.0

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G



# J0014A



## PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

### NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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